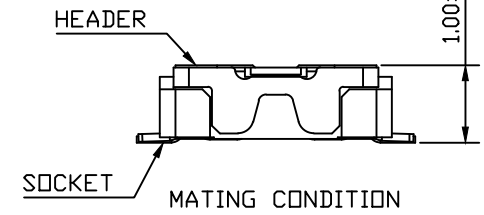


RECOMMENDED PCB PATTERN

- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0(LCP); COLOR:BLACK.
 - CONTACT: PHOSPHOR BRONZE(C5191)
 - FITTING NAIL:PHOSPHOR BRONZE(C5191)
 - FINISH:
 - CONTACT:SEE ORDER INFORMATION.
 - UNDERPLATING: 50~100u" NICKEL OVERALL.
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-51023-xxxxx
 - PACKAGE PLS. REFER TO 51023-XXXCR-XX
 - MATING CONNECTOR P/N:51024
 - PART NUMBER

51023-XXX X X-001

- CKTS _____
- PACKING _____
- 0.TAPE REEL _____
- 001: NORMAL
- BS1: PLASTIC REEL
- CONTACT PLATING
- 1.G/F ON CONTACT
- 5.3u" GOLD ON CONTACT AND SOLDER
- 8:20u" GOLD ON CONTACT AND SOLDER
- B:5u" GOLD ON CONTACT AND SOLDER



| DIM | A | B | C |
|-------|-------|------|-------|
| 20Pin | 5.80 | 3.60 | 5.20 |
| 24Pin | 6.60 | 4.40 | 6.00 |
| 30Pin | 7.80 | 5.60 | 7.20 |
| 40Pin | 9.80 | 7.60 | 9.20 |
| 50Pin | 11.80 | 9.60 | 11.20 |

| | | | | |
|---|-----------------|-----------|---|-----------------|
| QUALITY SYMBOLS MAJOR Ⓢ CRITICAL Ⓢ | DRAWN BY | DATE | | |
| | TSO I CHIAO | 23/07/31 | | |
| GENERAL TOLERANCES (UNLESS SPECIFIED) | CHECKED BY | DATE | TITLE 0.4mm 1.0H BOARD TO FPC CONN ,HEADER | |
| | Chen, Chun Yuan | 23/07/31 | | |
| X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2° | APPROVED BY | DATE | SIZE | DWG NO. |
| | Huang Kuo Hua | 23/07/31 | A4 | 51023-XXXXX-XXX |
| | UNITS | | REV | PART NO. |
| | mm | | G | SEE NOTES |
| | SCALE | SHEET NO. | | |
| | 10 : 1 | 1 OF 1 | | |